



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-04-25
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Patrick Crudo	Representative Title	MMS MD CHAMPION
Representative Phone *	(+33) 442 688 339	Representative Email *	patrick.crudo@st.com
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/online_tech_support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST92F150JDV1QCE	EE5F*9E1XXXY	A	9991	2016-04-25
Amount		UoM	Unit type	ST ECOPACK Grade
1773		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
QFP	14x20x2.7	100	L bend	
Comment	Package: PQFP 100 14x20x2.7 1.6			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EESP*9E1XXXY					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	22.435	mg	supplier	die	Silicon (Si)	7440-21-3		21.393	mg	953555	12066
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.258	mg	11500	146
die (s)				supplier	metallization	Copper (Cu)	7440-50-8		0.258	mg	11500	146
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.052	mg	2318	29
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.018	mg	802	10
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.041	mg	1828	23
die (s)				supplier	passivation	Indium Tin oxide (In2O3.SnO2)	50926-11-9		0.415	mg	18498	234
Encapsulation	Other inorganic materials	1155.308	mg	supplier	Molding Compound	Silica Fused	60676-86-0		1001.650	mg	866998	564946
Encapsulation				supplier	Molding Compound	Epoxy Resin	Trade secret		86.650	mg	75002	48872
Encapsulation				supplier	Molding Compound	Phenol resin	Trade secret		63.542	mg	55000	35839
Encapsulation				supplier	Molding Compound	Carbon Black	1333-86-4		3.466	mg	3000	1955
Leadframe	Other inorganic materials	585.140	mg	supplier	Copper Alloy	Copper (Cu)	7440-50-8		550.940	mg	941552	310739
Leadframe				supplier	Copper Alloy	Nickel (Ni)	7440-02-0		15.000	mg	25635	8460
Leadframe				supplier	Copper Alloy	Silicon (Si)	7440-21-3		3.000	mg	5127	1692
Leadframe				supplier	Copper Alloy	Magnesium (Mg)	7439-95-4		0.600	mg	1025	338
Leadframe				supplier	Copper Alloy	Silver (Ag)	7440-22-4		15.600	mg	26660	8799
Die Attach	Other inorganic materials	4.300	mg	supplier	Glue	Silver	7440-22-4		2.752	mg	640000	1552
Die Attach				supplier	Glue	Bismaleimide monomer	Trade Secret		0.344	mg	80000	194
Die Attach				supplier	Glue	Maleimide resin	Trade Secret		0.344	mg	80000	194
Die Attach				supplier	Glue	Bismaleimide resin	Trade Secret		0.344	mg	80000	194
Die Attach				supplier	Glue	Copper(II) oxide	1317-38-0		0.129	mg	30000	73
Die Attach				supplier	Glue	Vinyl	TS ref		0.129	mg	30000	73
Die Attach				supplier	Glue	2,6-Diglycidyl phenyl allyl ether oligomer	UNASSIGNED		0.129	mg	30000	73
Die Attach				supplier	Glue	Carbamate resin	TS ref		0.129	mg	30000	73
Bonding wire	Other inorganic materials	4.200	mg	supplier	Wire	Au	7440-57-5		4.200	mg	1000000	2369
Finishing	Other inorganic materials	1.617	mg	supplier	Connection coating	Tin(II) methanesulphonate	53408-94-9		0.808	mg	499691	456
Finishing				supplier	Connection coating	Methane sulfonic acid	75-75-2		0.081	mg	50093	46
Finishing				supplier	Connection coating	Water	7732-18-5		0.728	mg	450216	411